

**IN THE SPECIFICATION:**

The paragraph beginning on page 4, prenumbered line 16, has been amended as follows:

--The first dielectric layer 231, the second dielectric layer 232 and the third dielectric layer 233 are made of dielectric materials such as polyimide, epoxy, BT resin FR-4 resin, FR-5 resin, BCB (benezo cyclobutene) or PTFE (polytetrafluoroethylene), etc and are formed in turn on the active surface 211 of the die 210 and the surface 222 of the metal carrier 220. The first dielectric layer 231 formed on the active surface 211 of die 210 and the surface 222 of metal carrier 220 has a plurality of conductive columns 241. The conductive columns 231 are vertically bonded on the corresponding bonding pads 214 of the die 210 for electrical connection. The second dielectric layer 232 is formed on the first dielectric layer 231 and also has a plurality of conductive columns 242. Some of conductive columns 242 of the second dielectric layer 232 are vertically bonded on the conductive columns 241 of the first dielectric layer 231. The third dielectric later layer 233 is formed on the second dielectric layer 232 and has a plurality of conductive columns 243. A plurality of conductive pads 250 are formed on the third dielectric later layer 233. It is better that the conductive pads 250 are in grid array fashion. The conductive columns 243 electrically connect with the conductive columns 242 of the second dielectric layer 232 and the conductive pads 250. Some of conductive columns 243 of the third dielectric layer 233 are vertically bonded on the conductive columns 242 of the second dielectric layer 232. There are conductive traces 240 between dielectric layers 231, 232, 233 to electrically connect conductive columns 241, 242 and 243. Therefore, the bonding pads 214 of the die 210 electrically connect with the corresponding conductive pads 250 on the third dielectric layer 233. The conductive columns 241, 242 and 243 are made of copper, aluminum or their alloys for providing excellent electrical connections. Besides, solder balls 260, bumps or pins are formed on the conductive pads 250 for surface-mounting the semiconductor build-up package 200 to print circuit board, etc.--